

## Freescale Semiconductor Product Brief

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# i.MX27 PDK 1.0 Product Brief

The i.MX27 Product Development Kit (PDK) provides full-scale development implementation for the Freescale Semiconductor multimedia integrated applications processors.

This robust hardware and software platform for the Microsoft® Windows Embedded CE 6.0, and Linux® environments is based on the exceptional capability provided by the Freescale i.MX27 applications processor. The development kit offers optimized middleware and codecs, allowing your critical resources to focus on what makes your product unique, because Freescale has already completed the fundamental elements for your design.

The PDK includes an optimized and validated board support package (BSP), which is upgradeable by using additional hardware modules or by accessing key codecs. The BSP is one-half the cost of the original Freescale ADS development kit.

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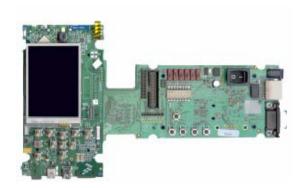
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Developers perform design and application work using the i.MX27 PDK, which comprises a "stack" of three separate modules, connected together for software development and debugging purposes, and packaged in a plastic enclosure. The module set, designed for essential re-use, includes the CPU, Debug, and Personality modules. The Debug module provides the common interface for the CPU and Personality modules. It also provides the functions for a software engineer to develop applications and any accompanying software. The Personality module is a peripheral and connectivity board for product development.



#### 1 Benefits

Developers can use this platform as a reference design, and begin immediately on their multimedia projects, with a near-end product platform. Hardware designers can develop a custom product quickly and software designers can begin long in advance of having any custom hardware. The integrated design methodology (hardware and software) greatly reduces your development time.

## 2 Features

The i.MX27 PDK provides the following features, which support its architecture, design, operation, and functionality:

- Near form-factor demonstration modules and working platforms.
- Solid reference schematics that closely resemble final products to aid customers' designs.
- CPLD Files
- Three-board system:
  - CPU board with i.MX27 ARM926<sup>TM</sup> MCU, MC13783 Atlas chip
  - Personality board with peripheral components and interface connectors
  - Debug board with two RS-232 interfaces, 10/100 Base-T Ethernet connector, and current measure connectors
- 2.8 inch TFTLCD display panel with touch panel and LED backlight
- 2.4 inch QVGA smart display panel connector
- Image sensor camera connector



- Smart Speed Technology
- 256 MB of NAND Flash Memory
- 128 MB of 32-bit DDR SDRAM memory
- Stereo microphone jack, headphone and video jack, stereo and mono (ear piece) speaker terminals
- One connector to outboard GPS module
- FM Receiver
- TV decoder that supports 8-bit color and NTSC & PAL format
- SD card connectors, with card sense functionality
- One USB OTG high-speed transceiver with miniature USB connector
- ATA5 controller with one 44-position dual row 2mm header for small form-factor disk drivers, and one 40 pin ZIF connector for Toshiba HDD
- Onboard accelerometer with sensitivity in three separate axes (X, Y, and Z)
- Two RS-232 interfaces with DB-9 connectors: one is driven by a UART channel internal to the MX27 and supports DCE with optional full modem controls; the other is DTE with optional full modem controls

## 3 System Requirements

The system requirements are as follows:

- IBM PC or compatible computer with Microsoft Windows 98, Windows ME, Windows 2000, Windows XP, or Windows NT (version 4.0) operating system
- +5VDC, 2.4A power supply with a female (inside positive) power connector (included)



## 3.1 Block Diagrams

Figure 1, Figure 2, and Figure 3 illustrate the functional modules of the i.MX27 PDK Debug board, CPU board, and Personality board, respectively.

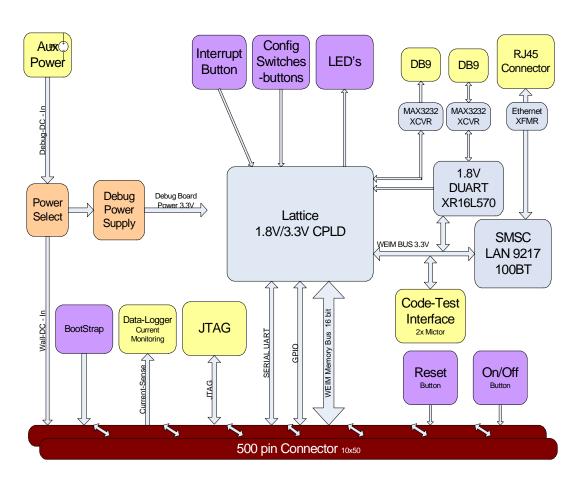


Figure 1 Debug Board Functional Block Diagram



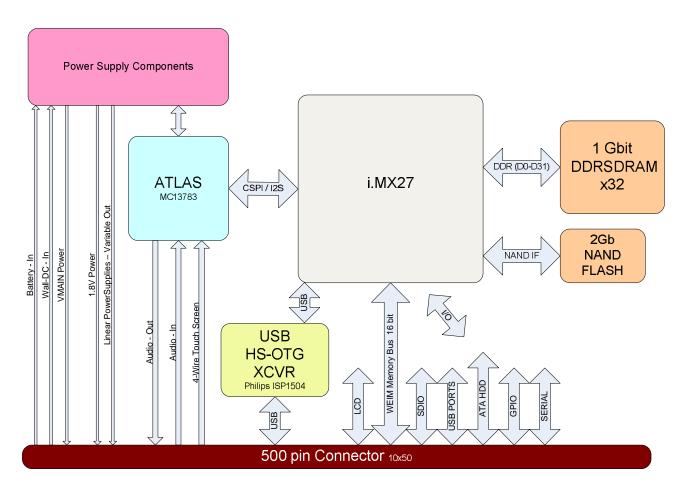


Figure 2 CPU Engine Board Block Diagram



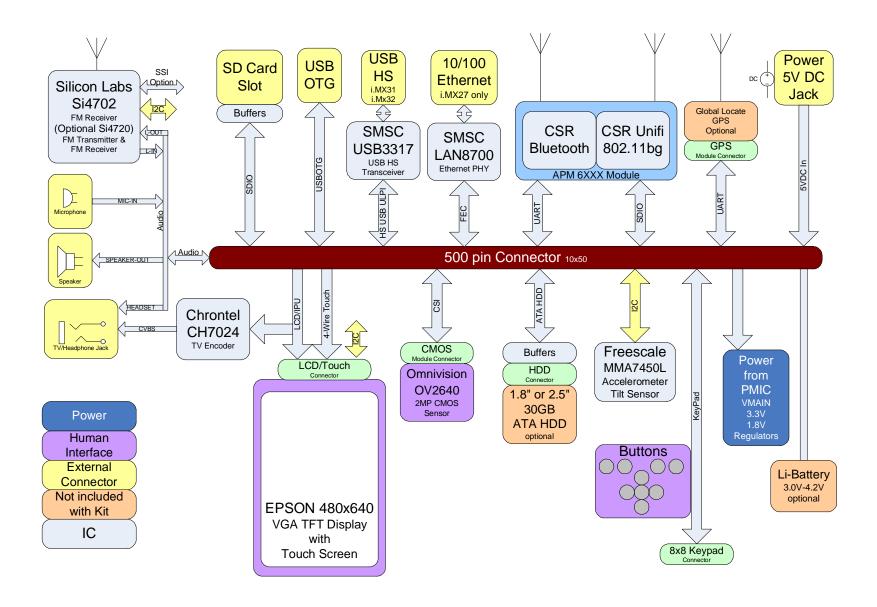


Figure 3 Personality Board Functional Block Diagram



## 3.2 Physical Connectors

- 10/100 Base-T Ethernet RJ45 connector
- WEIM Data and Address measure connector
- i.MX27 JTAG connector
- Samtec 500 pins board-to- board connector
- UART DB9 male connector and UART DB9 female connector
- 2.0M pixel CMOS sensor connector
- Debug port for Wi-Fi® and Bluetooth<sup>TM</sup> module
- 40 pin ZIF connector for Toshiba HDD
- Epson VGA LCD connector
- 44-position dual row, 2mm header for HDD
- SD card socket
- Current measure connector
- 2 mini USBOTG connectors, one for HOST connection only. The host connector is not used in the i.MX27 PDK.
- Giantplus QVGA Smart display connector
- GPS module connector
- Audio and Video connector



## 4 Product Documentation

The table that follows describes the associated documentation.

	Title	Contents	Document Number
Quick	Start Guides		
1	i.MX27 PDK 1.0 Quick Start Guide for Windows CE 5.0/ Windows Embedded CE 6.0	Detailed startup steps, using provided images	926-23574
2	i.MX27 PDK 1.0 Linux Quick Start Guide	Detailed startup steps, using provided images	926-23573
Overv	riew Documentation		
3	i.MX27 PDK 1.0 Product Brief (this document)	PDK benefits and attributes	926-78053
Hardy	vare Documentation		
4	i.MX27 PDK 1.0 Hardware User's Guide	Hardware description and reference	924-76325
5	i.MX27 PDK 1.0 GPS-B User's Guide	Description, connection, and procedures	926-77475
Applic	cation Notes		
6	i.MX27 PDK 1.0 Power Measurement Application Note	How to take application power measurements	926-77273
7	i.MX27 PDK 1.0 Enclosure Assembly Application Note	Enclosure kit contents and assembly	926-77673
8	i.MX27 PDK 1.0 Enclosure Kit Field Assembly Application Note	Building a PDK development platform	926-78298
9	i.MX27 PDK 1.0 Windows Revision Changes Application Note	Windows platform revision changes	926-77735
10	i.MX27 PDK 1.0 Linux Revision Changes Application Note	Linux platform revision changes	926-77774
11	Instructions to rework i.MX31 PDK Personality board to enable i.MX27 FEC functionality – Application Note	Modification instructions	DOC-23250
ATK [	Documentation		
12	i.MX PDK 1.0 Advanced ToolKit User's Guide	Installation, setup, operation	926-77203
13	i.MX PDK 1.0 Advanced ToolKit Reference Manual	Driver and software reference	924-76333
14	i.MX PDK 1.0 Advanced ToolKit Release Notes	Release contents, requirements, features, issues	924-76334
Windo	ows Embedded CE 6.0 Documentation		
15	i.MX27 PDK 1.0 Windows Embedded CE 6.0 Hello World Application Note	Hello World demo and new demo instructions	924-76323



	Title	Contents	Document Number			
16	i.MX27 PDK 1.0 Windows Embedded CE 6.0 Demo Image Readme	Release contents, installation, setup, requirements, features, issues	924-76321			
17	i.MX27 PDK 1.0 Windows Embedded CE 6.0 Release Notes	Release contents, requirements, features, issues	924-76320			
18	i.MX27 PDK 1.0 Windows Embedded CE 6.0 User's Guide	Application description and procedures, including ATK download	926-78096			
19	i.MX27 PDK 1.0 Windows Embedded CE 6.0 Reference Manual	Driver and software reference	926-78097			
Linux Documentation						
20	i.MX27 PDK 1.0 Linux Hello World Application Note	Hello World demo and new demo instructions	924-76323			
21	i.MX27 PDK 1.0 Linux Demo Image Readme	Release contents, installation, setup, requirements, features, issues	924-76327			
22	i.MX27 PDK 1.0 Linux Standard Package Release Notes	Release contents, requirements, features, issues	926-78095			
23	i.MX27 PDK1.0 Linux Standard User's Guide	Application description and procedures, including ATK download	926-78093			
24	i.MX PDK 1.0 Linux Reference Manual	Driver and software reference	926-78094			



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